



750V 200A Trench and Field Stop IGBT

Preliminary data

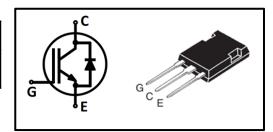
Features

- Easy parallel switching capability due to positive temperature coefficient in V_{CEsat}
- Low V_{CEsat}, fast switching
- High ruggedness, good thermal stability
- Very tight parameter distribution

Applications

- Motor drives
- Main inverter
- **■** PTC heater

Туре	Marking	Package Code
AMPBQ200N75GS	AB200N75GSFA	TO-247-3L
FA	ADZUUN/3G3FA	Plus



Maximum Rated Values

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V _{CE}	750	V
DC collector current, limited by T_{vjmax} $T_{C}=25^{\circ}C$ $T_{C}=100^{\circ}C$	I _C	200 200	
Pulsed collector current, t _p limited by T _{vjmax} 1)	I _{Cpuls}	600	
Diode forward current, limited by T _{vjmax} T _C =25°C T _C =100°C	I _F	200 200	A
Diode pulsed current, t _p limited by T _{vjmax} 1)	I _{Fpuls}	600	
Gate-emitter voltage	V	±20	V
Transient Gate-emitter voltage (t _p ≤10us,D<0.01)	V_{GE}	±30	·
Short circuit withstand time $V_{GE}=15V$, $V_{CC}\leq470V$, $T_{vj}=25^{\circ}C$ Allowed number of short circuits < 1000 Time between short circuits: $\geq 1.0s$	t _{SC}	5	μs
Power dissipation T _C =25°C	Б	1071	١٨/
Power dissipation T _C =100°C	P _{tot}	535	W
Operating junction temperature	T _{vj}	-40~175	
Storage temperature	T _{stg}	-55~150	_ ℃
Soldering temperature, wave soldering 1.6mm (0.063in.) from case for 10s		260	
Mounting torque, M3 screw Maximum of mounting processes: 3	М	0.6	Nm

¹⁾ Defined by design. Not subject to production test.

AMPBQ200N75GSFA Preliminary data

Thermal Characteristics

Parameter	Symbol	Min	Тур	Max	Unit
IGBT thermal resistance, junction-case	R _{thJC}	ı	1	0.14	
Diode thermal resistance, junction-case	R _{thJCD}	ı	1	0.26	K/W
Thermal Resistance, junction-ambient	R _{thJA}	-	-	40	

Electrical Characteristics (at $T_{\nu j}$ =25°C, unless otherwise specified) Static Characteristics

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter breakdown voltage	V _{(BR)CES}	V _{GE} =0V, I _C =0.25mA	750	1	1	
Collector-emitter saturation voltage	$V_{CE(sat)}$	V _{GE} =15V, I _C =200A T _{vi} =25°C	ı	1.5	1.7	V
		T _{vj} =150°C	ı	1.71	-	V
		T _{vj} =175°C	-	1.75	-	
G-E threshold voltage	$V_{GE(th)}$	I_C =2.6mA, V_{CE} = V_{GE}	5.0	5.8	6.5	
C-E leakage current	I _{CES}	V_{CE} =750V, V_{GE} =0V T_{vi} =25°C	ı	1	0.01	mA
J		T _{vj} =175°C	-		4.0	
G-E leakage current	I _{GES}	V _{CE} =0V, V _{GE} =20V	-	-	250	nA

Dynamic Characteristics

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Input capacitance	C _{iss}		-	17855	-	
Output capacitance	C _{oss}	V _{CE} =25V, V _{GE} =0V,	-	608	-	pF
Reverse transfer capacitance	C _{rss}	f=100KHz	-	122	-	·
Gate charge	Q_{G}	V _{CC} =600V, I _C =200A, V _{GE} =15V	ı	tbd	-	nC
Short circuit collector current	I _{C(SC)}	V _{GE} =15V, V _{CC} ≤470V, t _{SC} ≤5μs, T _{vj} =25°C	-	950	-	А



IGBT Switching Characteristics

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Turn-on delay time	t _{d(on)}		-	202	-	
Rise time	t _r	T _{vi} =25°C,	-	109	-	
Turn-off delay time	t _{d(off)}	V _{CC} =470V,	-	365	1	ns
Fall time	t _f	I _C =200A, V _{GE} =-8/15V,	-	70	1	
Turn-on energy	E _{on}	$R_{G}=5\Omega$,	-	19.4	ı	
Turn-off energy	E _{off}	Inductive load	-	10.6	ı	mJ
Total switching energy	E _{ts}		-	30.0	-	
Turn-on delay time	t _{d(on)}		-	214	ı	
Rise time	t _r] T _{vj} =175℃,	-	173	•	
Turn-off delay time	t _{d(off)}	V _{CC} =470V,	-	422	•	ns
Fall time	t _f	I _C =200A, V _{GE} =-8/15V, R _G =5Ω, Inductive load	-	93	•	
Turn-on energy	E _{on}		-	34.9	1	
Turn-off energy	E _{off}		-	13.5	-	mJ
Total switching energy	E _{ts}		-	48.4	-	

Diode Characteristics

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Diode forward voltage	V _F	V _{GE} =0V, I _F =200A T _{vi} =25°C	-	1.65	-	V
Diode forward voltage	VF	T _{vj} =150°C	-	1.83	-	V
		T _{vj} =175°C	-	1.85	-	
Diode reverse recovery time	t _{rr}	T _{vi} =25°C,	-	435	-	ns
Diode reverse recovery charge	Q _{rr}	V _R =470V, I _E =200A,	-	9.4	-	μC
Diode peak reverse recovery current	I _{rrm}	di _F /dt=1810A/µs	-	41	-	А
Diode reverse recovery time	t _{rr}	T _{vi} =175°C,	1	541	-	ns
Diode reverse recovery charge	Q _{rr}	V _R =470V, I _F =200A,	-	17.4	-	μC
Diode peak reverse recovery current	I _{rrm}	di _F /dt=1250A/µs	-	47	-	А



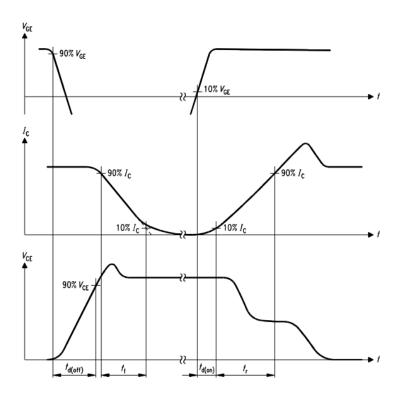


Figure A. Definition of switching times

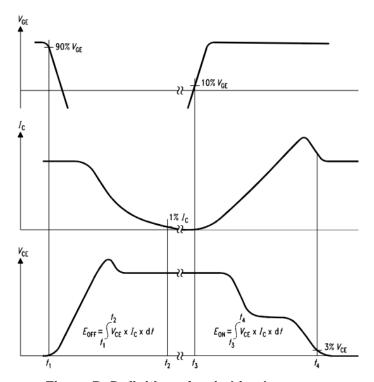


Figure B. Definition of switching losses

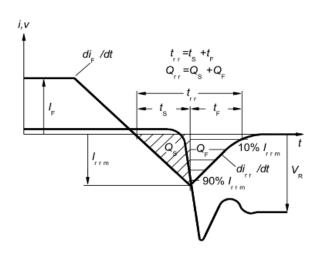


Figure C. Definition of diodes switching characteristics

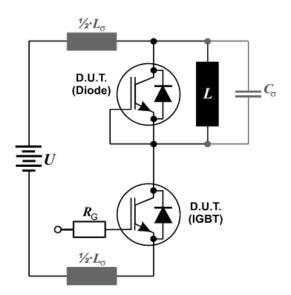
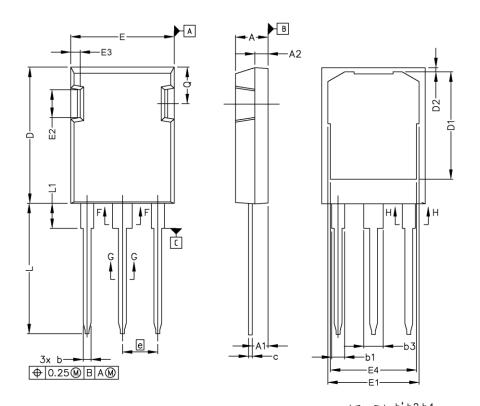


Figure D. Switching test circuit



TO-247-3L Plus



SYMBOL	MIN	MAX		
A	4.83	5.21		
A1	2.29	2.54		
A2	1.91	2.16		
b'	1.07	1.28		
b	1.07	1.33		
b1	1.91	2.41		
b2	1.91	2.16		
b3	2.87	3.38		
b4	2.87	3.13		
c'	0.55	0.65		
С	0.55	0.68		
D	20.80	21.10		
D1	16.25	17.65		
D2	0.50	0.80		
Е	15.75	16.13		
E1	13.10	14.15		
E2	3.68	5.10		
E3	1.00	1.90		
E4	12.38	13.43		
e	5.44 BSC			
N	3			
L	19.81	20.32		
L1	3.70	4.00		
Q	5.49	6.00		

- NOTE;

 1. ALL METAL SURFACES: TIN PLATED, EXCEPT AREA OF CUT

 2. DIMENSIONING & TOLERANCEING CONFIRM TO

 ASME Y14.5M-1994.

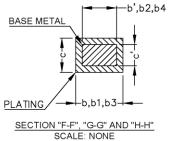
 3. ALL DIMENSIONS ARE IN MILLIMETERS.

 ANGLES ARE IN DEGREES.

 4. THIS DRAWING WILL MEET ALL DIMENSIONS REQUIREMENT

 OF JEDEC outlines TO-247 AD.

- 1 GATE
- 2 DRAIN (COLLECTOR)
- 3 SOURCE (EMITTER) 4 DRAIN (COLLECTOR)





AMPBQ200N75GSFA Preliminary data

Revision History

Revision	Subjects (major changes since last revision)	Date
0.1	Preliminary data	2023.7
0.2	Add data	2023.9

Terms & Conditions of usage

- 1. The product specifications, characteristics, data, materials and structures given in this datasheet are subject to change without notice.
- 2. The information given in this datasheet shall in no event be regarded as a guarantee of conditions or characteristics. Marching-Power Technology Co., Ltd. does not warrant or assume any legal liability or responsibility for the accuracy and completeness of any examples, hints or any typical values stated herein and/or any information regarding the application of the product.
- 3. This datasheet is only used as a reference for customers to apply our products, Marching-Power Technology Co., Ltd. does not undertake to permit the use of intellectual property rights or any third-party property rights related to the product information described in this datasheet.
- 4. Although Marching-Power Technology Co., Ltd. is committed to enhancing product quality and reliability, all semiconductor products still have a probability of failure. When using Marching-Power semiconductor products in your equipment, you are requested to take adequate safety measures to prevent the equipment from causing accidents or events including but not limited to physical injury, fire or damage to other property if any of the products become faulty.
- 5. The products introduced in this datasheet are electrostatic sensitive devices and must be protected against static electricity during device installation, testing, packaging, storage and transportation.
- 6. Do not use the products introduced in this datasheet in equipment or systems that requiring strict reliability or/and may directly endanger human life such as medical, life-saving, life-sustaining, space equipment, aeronautic equipment, nuclear equipment submarine repeater equipment and equivalents to strategic equipment (without limitation).
- 7. No part of this datasheet may be disseminated and reproduced in any form or by any means without prior written permission from Marching-Power Technology Co., Ltd.
- 8. The data contained in this datasheet is exclusively intended for use by professional technicians only. It is the responsibility of the customer's own technical departments to evaluate the suitability of the product for the intended application and the completeness of the product information given in this document with respect to corresponding application. If you have any question about any portion in this datasheet, contact Marching-Power Technology Co., Ltd. before using the product. Marching-Power Technology Co., Ltd. shall not be liable for any injury caused by any use of the products not in accordance with instructions set forth herein.